MATERIAL DATA FORM

Manufacturer contact Information	
Contact Name	Richard Bush
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Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Substance Name	IMDS No.	Substance Mass (mg)	% Weight of Assembly	PPM of Total Assembly
DVRxVxW	0.006	Die, ASMCC	Doped silicon	TBD	0.4571	7.46%	74587
Customer's Partnumber.		SOT-363 leadframe	Alloy 42	10791142	1.9641	32.05%	320476
			Die attached pad plating	37507916	0.0606	0.99%	9896
		Bonding wire	Gold	3399000	0.0296	0.48%	4828
		Molding compound	CEL-1702HF-9	28644240	3.5348	57.68%	576764
		Tin solder	Pure Tin	37508652	0.0824	1.34%	13450
				Total（mg）	6.129		

MATERIAL DATA FORM DETAIL

Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Generic ID	Element	CAS No.	Substance Mass (mg)	% of Weight (Sub Assembly Material)	PPM of Sub Assembly Material	PPM of Total Weight	Additional Information (e.g. complete polymeric Material Trade Name or metallic Material Standard). Please declare "No FR" when the polymeric material	Manufacturer Part & Version No.	Date of completion. dd/mm/yyyy	Dummy No.	Customer Project.	Diodes ECN No.	Manufacturer DUNS Number
DVRxVxW	0.006	Die, ASMCC	Doped silicon	Si	7440-21-3	0.4571	100.00%	1000000	74587							
Customer's Partnumber.		SOT-363 leadframe	Alloy 42	Fe	7439-89-6	1.1323	57.65%	576500	184754							
				Ni	7440-02-0	0.8053	41.00%	410000	131395							
				Mn	7439-96-5	0.0118	0.60%	6000	1923							
				Cr(not Cr 6+)	7440-47-3	0.0020	0.10%	1000	320							
				Co	7440-48-4	0.0098	0.50%	5000	1602							
				Si	7440-21-3	0.0029	0.15%	1500	481							
			Pure silver	Ag	7440-22-4	0.0606	100.00%	1000000	9896							
		Bonding wire	1.0mil	Au	7440-57-5	0.0296	100.00%	1000000	4828							
		Molding compound	CEL-1702HF-9	SiO2	60676-86-0	3.0858	87.30%	873000	503515							
				Epoxy Resin	29690-82-2	0.1767	5.00%	50000	28838							
				Phenol Resin	26834-02-6	0.1767	5.00%	50000	28838							
				Aromatic poly-ph	----	0.0884	2.50%	25000	14419							
				C	1333-86-4	0.0071	0.20%	2000	1154							
		Tin solder	Pure Tin	Sn	7440-31-5	0.0824	100.00%	1000000	13450							
					Total（mg）	6.129										

Not intentionally added the following material **EXCEPT AS NOTED ABOVE**:

1. Cadmium and cadmium compounds
2. Lead and lead compounds
3. Mercury and mercury compounds
4. Hexavalent chromium compounds
5. Polybrominated biphenyls (PBB) and Polybrominated biphenyl ethers (PBDE)
6. Chlorinated organic compounds
7. Organic tin compounds
8. Asbestos
9. Azo compounds
10. diphenylether, pentabromo derivative C12H5Br5O
11. diphenylether, octabromo derivative C12H2Br8O

RoHS COMPLIANCE STATEMENT: Compliant with RoHS without exemption application

RoHS exemption application: None

MATERIALS DISCLOSURE DISCLAIMER

1. The materials are disclosed according to JIG-101 "Material Composition Declaration for Electronic Products"
2. Even though all possible efforts have been made to provide you with the most accurate information, we can not guarantee its completeness and accuracy due to the fact that the data has been compiled based on information provided by our subcontractors and raw material suppliers. Complete information may not have been provided to protect their business proprietary information. Based on the above considerations, this information is provided only as estimates of the average weight of these parts and the anticipated significant toxic metals components.
3. These estimates do not include trace levels of dopants and metal materials within the silicon devices contained inside of the finished products.